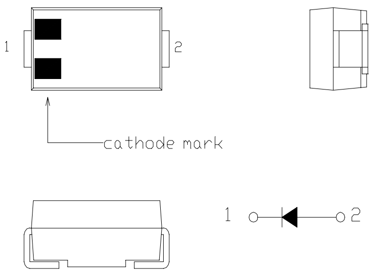
Nihon Inter Electronics Corporation

SBD Type : EC21QS06

FEATURES

- * Miniature Size,Surface Mount Device
- * Low Forward Voltage Drop
- * Low Power Loss,High Efficiency
- * High Surge Capability
- * 30 Volts through 100Volts Types Available
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC21QS06			Unit
Repetitive Peak Reverse Voltage	V_{RRM}	60			V
Non- repetitive Peak Reverse Voltage	V_{RSM}	65			V
Average Rectified Output Current	I_o	1.0	Ta=35 ℃ *1	50Hz Half Sine Wave Resistive Load	A
		2.0	Tl=90 ℃		
RMS Forward Current	$I_{F(RMS)}$	3.14			A
Surge Forward Current	I_{FSM}	40	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T_{jw}	-40 to +150			℃
Storage Temperature Range	T_{stg}	-40 to +150			℃

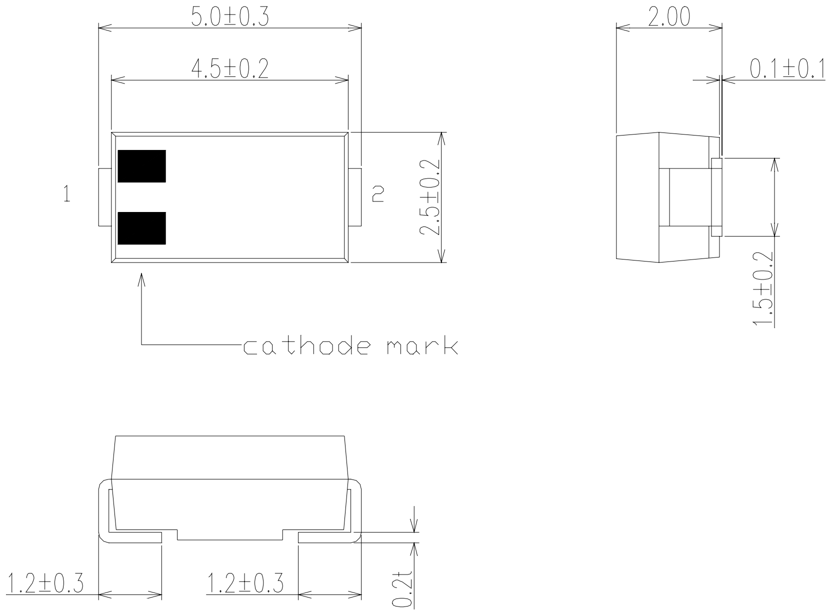
Electrical • Thermal Characteristics

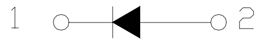
Characteristics		Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current		I_{RM}	Tj= 25℃, V_{RM}= V_{RRM}	-	-	2	mA
Peak Forward Voltage		V_{FM}	Tj= 25℃, I_{FM}= 2.0A	-	-	0.61	V
Thermal Resistance	Junction to Ambient	$Rth_{(j-a)}$	Alumina Substrate Mounted *1	-	-	108	℃ /W
	Junction to Lead	$Rth_{(j-l)}$	-	-	-	23	

*1 Alumina Substrate Mounted (Soldering Lands=2x2mm,Both Sides)

(Tl: Lead Temperature)

EC21QS06 OUTLINE DRAWING (Dimensions in mm)





soldering pad